

Preface

Dear Distinguished Authors and Guests,

The Organizing Committee warmly welcomes you to 2015 7th International Conference on Mechanical and Electronics Engineering (ICMEE 2015), held on September 26-27, 2015, in Dalian, China.

The aim of ICMEE 2015 is to present the latest research and results of scientists (professors, students, PhD Students, engineers, and post-doc scientist) related to Mechanical and Electronics Engineering topics. This conference provides opportunities for the different areas delegates to exchange new ideas and application experiences face to face, to establish business or research relations and to find global partners for future collaboration.

After the peer-review process, the submitted papers were selected on the basis of originality, significance, and clarity for the purpose of the conference. The selected papers and additional late-breaking contributions to be presented as lectures will make an exciting technical program. The conference program is extremely rich, featuring high-impact presentation. We hope that the conference results constituted significant contribution to the knowledge in these up to date scientific field.

The proceeding records the fully refereed papers presented at the conference. The main conference themes and tracks are Mechanical and Electronics Engineering etc. Hopefully, all participants and other interested readers benefit scientifically from the proceedings and also find it stimulating in the process.

On behalf of the organizing committee, I would like to especially thank Isaline Augusto and all the editors from EDP Sciences for their great support to ICMEE 2015. Without their excellent editorial work, ICMEE 2015 will not be published so timely and successfully.

All the organizing members will be committed us to make ICMEE more and more professional with fully and enjoyable academic research and discussion platform for authors and attendees. Sincerely as always, we look forward to your consistent attention and support to 8th ICMEE in 2016.

With our warmest regards,

Prof. Du Mingxing, Tianjin University of Technology, China
Prof. Xu Guosheng, Weifang University, China